|  |  |  |
| --- | --- | --- |
| C:\Users\ba\AppData\Local\Microsoft\Windows\Temporary Internet Files\Content.IE5\R9YC35I5\LG-0001-OHB_02_Logo OHB AG.jpg | **WE Inspektion Report** | Date: 22.03.2016 |
| **SO-CAU-OHB-RP-45** | | |
| **1. INSPECTED UNIT** | | |
| Projekt | CAU Solar Orbiter | |
| Part name / number: | STEP Digital Board | |
| Model | FM | |
| Serial number | AG 1 | |
| **2. INSPECTION TYPE** | | |
| Type of inspection (solder, coating, final …) | Wareneingang | |
|  | **P**ass/ **F**ail/ **C**omments | |
| Connectors/Saver | P | |
| Hardware assembly | C | |
| Gluing | P | |
| Soldering | C | |
| Cleanliness | P | |
| **3. RESULTS** | | |
| Part acceptable? | Verpackung in Ordnung, keine Beschädigungen keine Verunreinigungen auf der PCB | |
|  |  | |
| **4. COMMENTS** | | |
| Build to Manufacturing Flow Chart: STEP-Digital-Board-OHB-11-XI  U205 auf einer Seite auf ca. 0,1mm heruntergebogen  Solder Bridge „C215“ nicht ESA-Gerecht ausgeführt. Kein Stressrelief. | | |
| **5 SIGNATURE** | | |
| Inspection performed: S. Vital 22.03.2016  Name Date Signature | | |
|  | | |

|  |  |  |  |  |
| --- | --- | --- | --- | --- |
| **S/N:** AG 1   |  |  | | --- | --- | | **U205** | **Solder Bridge** | | **G:\DCIM\100NIKON\RSCN8299.JPG** | **G:\DCIM\100NIKON\RSCN8303.JPG** | |